UMW AO4884

40V Dual N-Channel MOSFET

1.Description

The AO4884 uses advanced trench technology to provide excellent $R_{DS(ON)}$ with low gate charge. This is an all purpose device that is suitable for use in a wide range of power conversion applications.

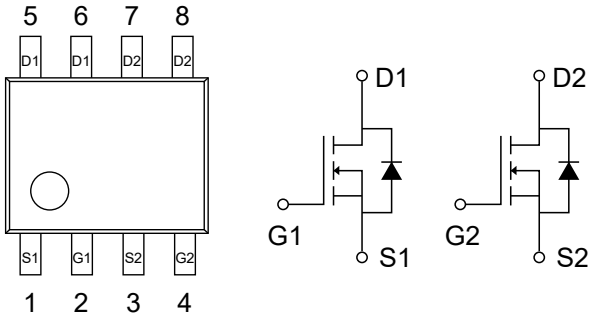
2.Features

- $V_{DS\ (V)}$=40V
- I_D=10A(V_{GS}=10V)
- $R_{DS(ON)}$<13mΩ(V_{GS}=10V)
- $R_{DS(ON)}$<16mΩ(V_{GS}=4.5V)

3.Pinning information

Pin	Symbol	Description
2,4	G1, G2	GATE
1,3	S1, S2	SOURCE
5,6,7,8	D1, D2	DRAIN

SOP-8



4.Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Rating	Units
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	±20	
Continuous Drain Current	T_A=25°C	I_D	10	A
	T_A=70°C		8	
Pulsed Drain Current [c]		I_{DM}	50	
Avalanche Current [c]		I_{AS}, I_{AR}	35	
Avalanche energy L=0.1mH [c]		E_{AS}, E_{AR}	61	mJ
Power Dissipation [B]	T_A=25°C	P_D	2	W
	T_A=70°C		1.3	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

5.Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	48	62.5	°C/W
Maximum Junction-to-Ambient [A D]	Steady-State		74	90	°C/W
Maximum Junction-to-Lead	Steady-State	$R_{\theta JL}$	32	40	°C/W

6.Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
Drain-Source Breakdown Voltage	BV_{DSS}	I_D=250μA, V_{GS}=0V	40			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=40V, V_{GS}=0V			1	μA
		T_J=55°C			5	
Gate-Body leakage current	I_{GSS}	V_{DS}=0V, V_{GS}=±20V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250μA	1.2	1.5	2.5	V
On state drain current	$I_{D(ON)}$	V_{GS}=10V, V_{DS}=5V	50			A
Static Drain-Source On-Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=10A		11	13	mΩ
		V_{GS}=4.5V, I_D=10A		12	16	mΩ
Forward Transconductance	g_{FS}	V_{DS}=5V, I_D=10A		50		S
Diode Forward Voltage	V_{SD}	I_S=1A, V_{GS}=0V		0.7	1	V
Maximum Body-Diode Continuous Current	I_S				2.5	A
DYNAMIC PARAMETERS						
Input Capacitance	C_{iss}	V_{GS}=0V, V_{DS}=20V, f=1MHz	1200	1500	1950	pF
Output Capacitance	C_{oss}		150	215	280	pF
Reverse Transfer Capacitance	C_{rss}		80	135	190	pF
Gate resistance	R_g	V_{GS}=0V, V_{DS}=0V, f=1MHz	1.7	3.5	5.3	Ω
SWITCHING PARAMETERS						
Total Gate Charge	Q_g(10V)	V_{GS}=10V, V_{DS}=20V, I_D=10A	22	27.2	33	nC
Total Gate Charge	Q_g(4.5V)		10	13.6	16	nC
Gate Source Charge	Q_{gs}		3.6	4.5	5.4	nC
Gate Drain Charge	Q_{gd}		3.8	6.4	9	nC
Turn-On DelayTime	$t_{D(on)}$	V_{GS}=10V, V_{DS}=20V, R_L=2Ω,R_{GEN}=3Ω		6.4		ns
Turn-On Rise Time	t_r			17.2		ns
Turn-Off DelayTime	$t_{D(off)}$			29.6		ns
Turn-Off Fall Time	t_f			16.8		ns
Body Diode Reverse Recovery Time	t_{rr}	I_F=10A, dI/dt=500A/μs	9	13	17	ns
Body Diode Reverse Recovery Charge	Q_{rr}	I_F=10A, dI/dt=500A/μs	25	35	45	nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in ^{2} FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(MAX)}$=150°C, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150°C. Ratings are based on low frequency and duty cycles to keep initial T_J=25°C.

D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedence which is measured with the device mounted on 1 in ^{2} FR-4 board with 2oz. Copper, assuming a maximum junction temperature of $T_{J(MAX)}$=150°C. The SOA curve provides a single pulse rating.

7.1TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

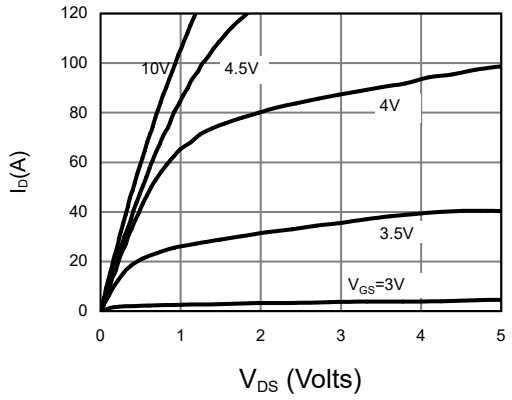


Fig 1: On-Region Characteristics (Note E)

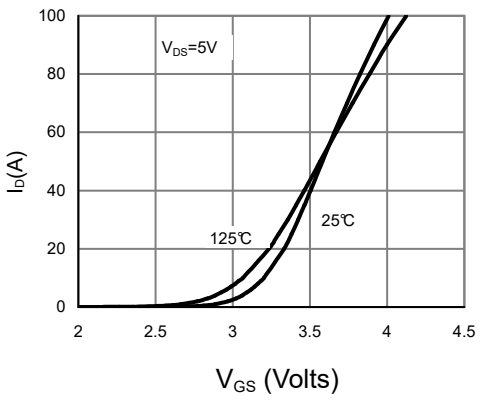


Figure 2: Transfer Characteristics (Note E)

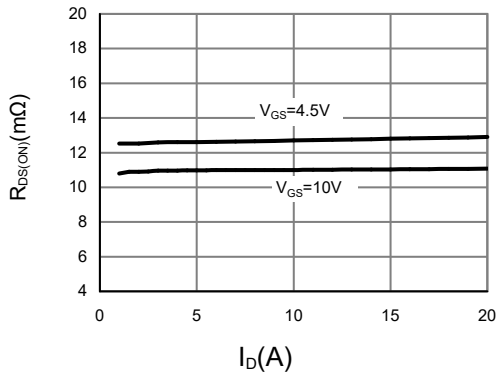


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

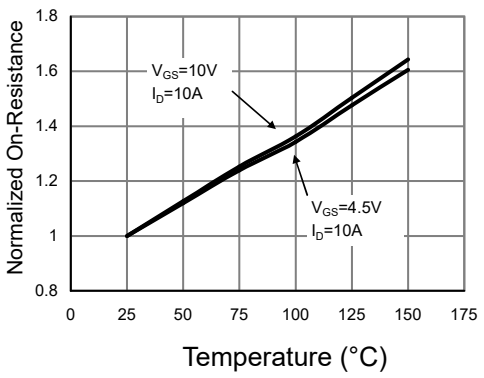


Figure 4: On-Resistance vs. Junction Temperature (Note E)

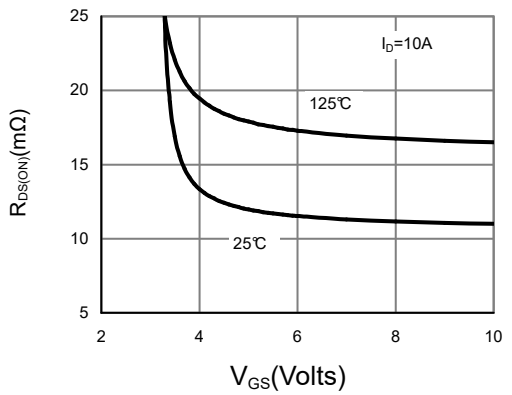


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

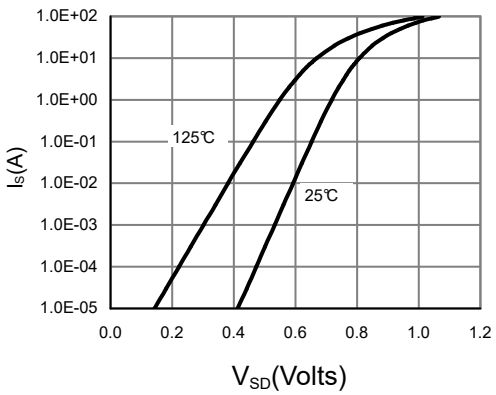


Figure 6: Body-Diode Characteristics (Note E)

7.2TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

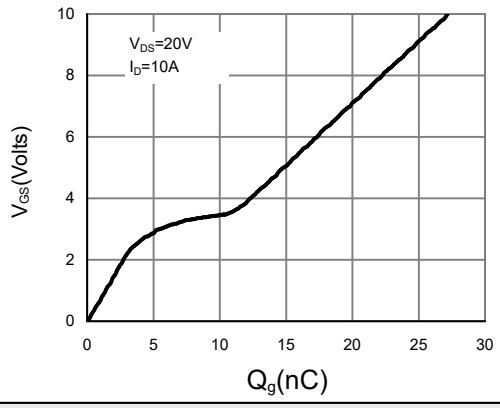


Figure 7: Gate-Charge Characteristics

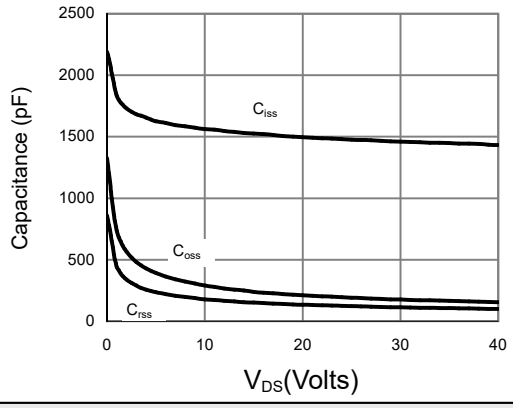


Figure 8: Capacitance Characteristics

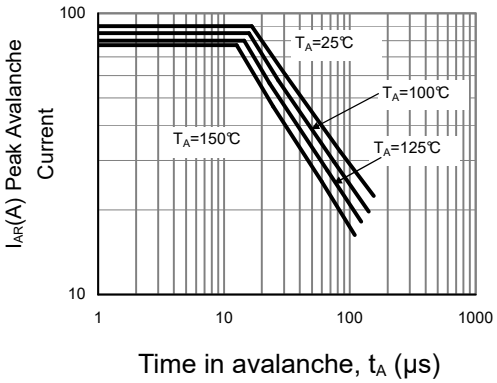


Figure 9: Single Pulse Avalanche capability (Note C)

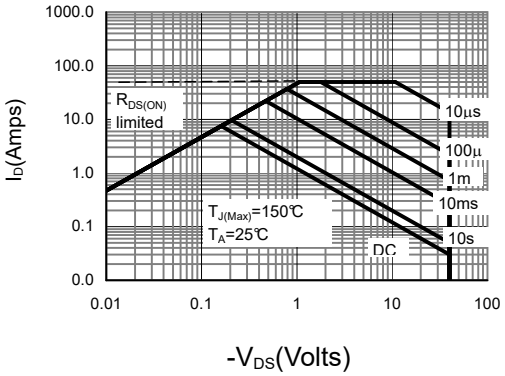


Figure 10: Maximum Forward Biased Safe Operating Area (Note F)

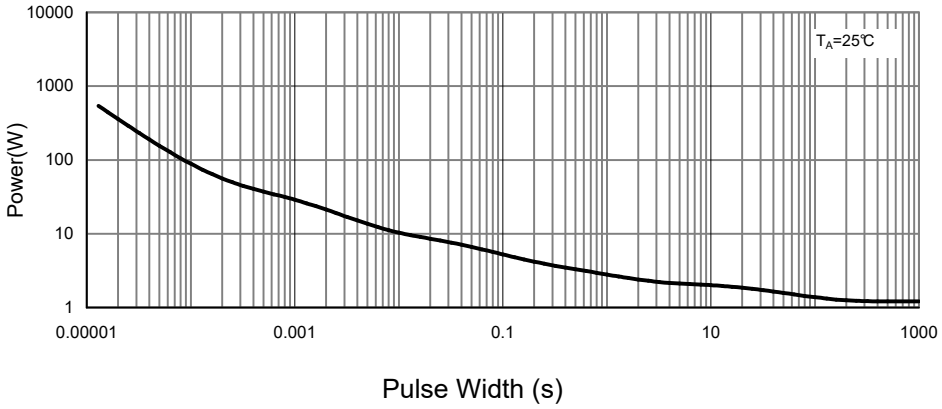


Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)

7.3TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

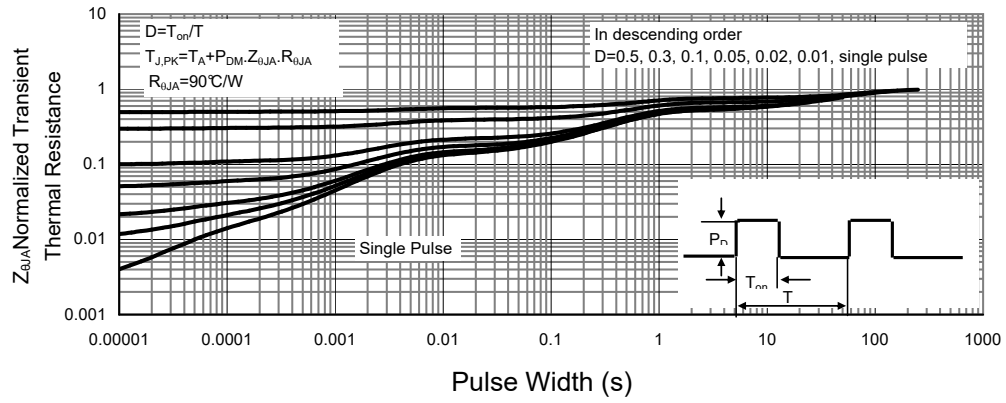
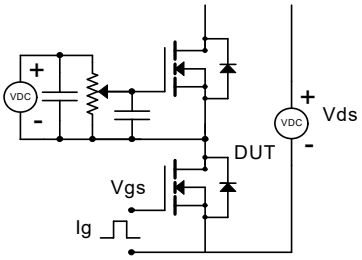
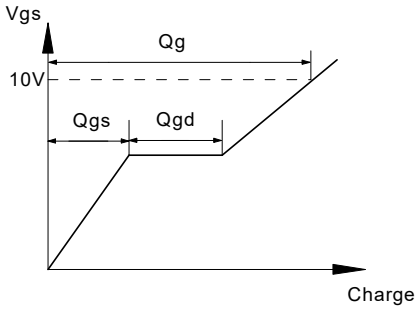


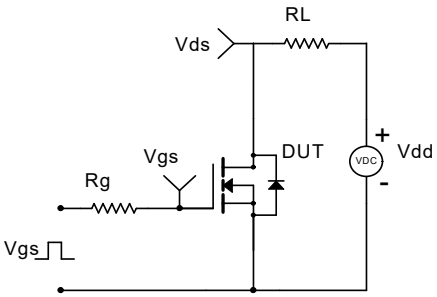
Figure 12: Normalized Maximum Transient Thermal Impedance (Note F)

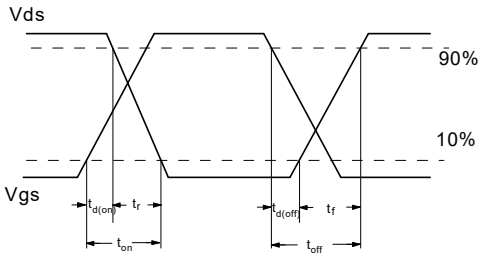
Gate Charge Test Circuit & Waveform



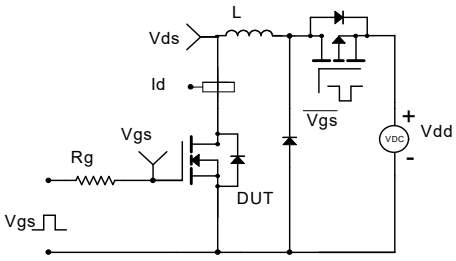


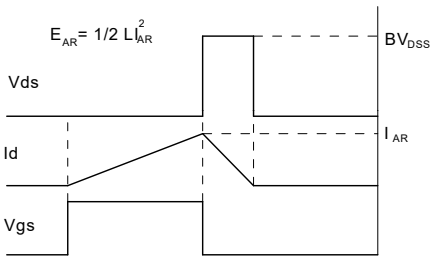
Resistive Switching Test Circuit & Waveforms



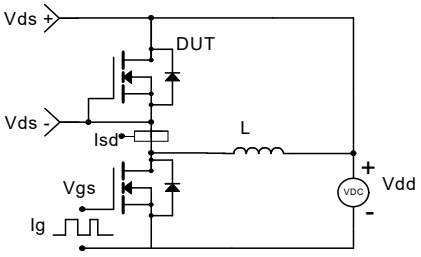


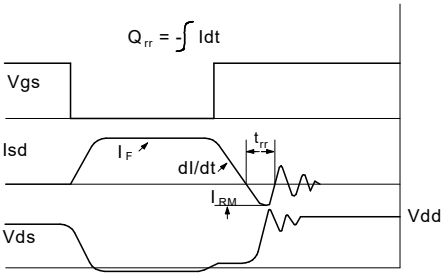
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



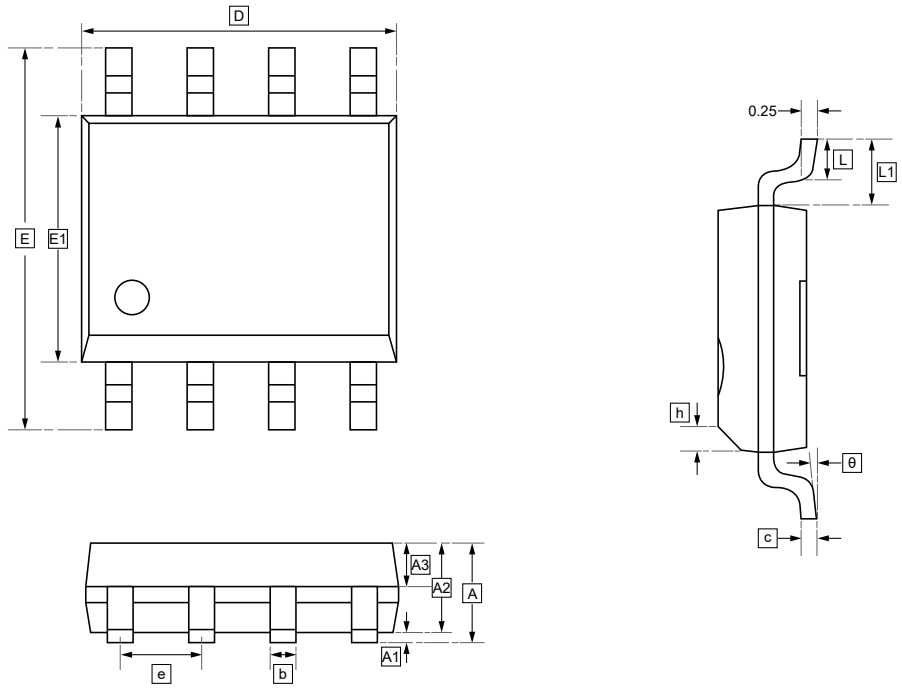


Diode Recovery Test Circuit & Waveforms





8.SOP-8 Package Outline Dimensions

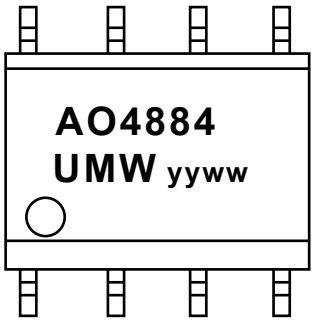


DIMENSIONS (mm are the original dimensions)

Symbol	A	A1	A2	A3	b	c	D	E	E1	e	h	L
Min	-	0.05	1.30	0.60	0.39	0.20	4.80	5.80	3.80	1.24	0.30	0.50
Max	1.75	0.20	1.50	0.70	0.47	0.24	5.00	6.20	4.00	1.30	0.50	0.80

Symbol	L1	θ
Min	1.00	0°
Max	1.10	8°

9.Ordering information



yy: Year Code
ww: Week Code

Order Code	Package	Base QTY	Delivery Mode
UMW AO4884	SOP-8	3000	Tape and reel

10.Disclaimer

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